

Electronic Patent Application Fee Transmittal

Application Number:	10563778			
Filing Date:	06-Jan-2006			
Title of Invention:	Hardenable pressure sensitive adhesive sheet for dicing/die-bonding and method for manufacturing semiconductor device			
First Named Inventor/Applicant Name:	Naoya Saiki			
Filer:	Kent E. Baldauf/Melissa Wyke			
Attorney Docket Number:	1217-053827			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 3 months with \$0 paid	1253	1	1110	1110

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				1110